

# Heterogeneous Integration Packaging Roadmap

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Heterogeneous Integration Roadmap is the Roadmap for the Next Era of Moore's Law paving the way towards Electronics Industry Resurgence decades into the future. It articulates state-of-the-art Advances in Technology & Science, Future directions, Roadblocks & Potential solutions. In this talk, we will present the Heterogeneous Integration roadmap from the conventional packaging technologies to the most advanced heterogeneous integrated 2.5D and 3D package. We will give a high-level introduction of the five major areas of the roadmap and all the twenty-three working groups covering total microelectronics systems and technology ecosystem. The five main areas include the Heterogeneous Integration Systems & Market Applications, Heterogeneous Integration Components, Cross-cutting topics, Heterogeneous Integration Processes, Co-design, and Simulation. Will focus on the chiplets/2.5D/3D packaging techniques, integration process, reliability and co-design and simulations.